

FEATURES & BENEFITS



easy application



dedicated to lead and lead-free solders

LOGISTIC DATA

Type	KONTAKT
Index Ergom	E05ML-01010300101
Quantity in package [pcs]	1
Weight [g]	40

APPLICATION

Mild, ready for direct use, non-corroding flux of paste consistence, made on the base of rosin and organic activating additives from chlorine free compounds. Applied in electrical and electronic engineering (also for printed circuits). Remnants of the paste after soldering cause no corrosion and may remain on welds.

